Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1748	257/783	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/06 16:15
L2	1997	257/707	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/06 16:15
S1	1599	257/783	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/07/13 16:22
S2	2097	257/686	USPAT	OR	OFF	2004/06/30 11:34
S3	1188	257/686 and (adhesive or glue)	USPAT	OR	OFF	2004/07/19 18:35
S4	1327	257/783	USPAT	OR	OFF	2004/06/30 11:18
S5	2628	257/686	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/06/30 11:34
S6	1188	257/686 and (adhesive or glue)	USPAT	OR	OFF	2004/06/30 11:35
S7	1440	257/686 not (257/686 and (adhesive or glue))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/06/30 15:55
S8	1859	257/707	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/06/30 16:17
S9	1995	438/108	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/06/30 16:55
S10	929	438/109	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/06/30 17:13

S11	3657	361/760	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/06/30 20:12
S12	1442	361/760 and (adhesive or glue)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/06/30 20:12
S13	3657	361/760	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/06/30 20:12
S14	3315	361/760	USPAT	OR	OFF	2004/06/30 20:12
S15	1442	361/760 and (adhesive or glue)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/06/30 20:12
S16	1945	361/760 not (361/760 and (adhesive or glue))	USPAT	OR	OFF	2004/06/30 20:18
S17	270	361/760 not (361/760 and (adhesive or glue))	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/06/30 20:19
S18	2649	257/686	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/13 16:23
S19	2111	257/686	USPAT	OR	ON	2004/07/13 16:23
S20	1485	257/686 and (adhesive or glue or insert$3 or under near fill$3)	USPAT	OR	ON	2004/07/13 18:04
S21	1	"5343075".PN.	USPAT	OR	OFF	2004/07/13 18:39
S22	1	"5952725".PN.	USPAT	OR	OFF	2004/07/13 18:52
S23	1	"6049124".PN.	USPAT	OR	OFF	2004/07/13 19:15
S24	1	"6351028".PN.	USPAT	OR	OFF	2004/07/13 19:16
S25	1	"6351028".PN.	USPAT	OR	OFF	2004/07/13 19:16
S26	1	"6576992".PN.	USPAT	OR	OFF	2004/07/13 19:16
S27	1	"5805422".PN.	USPAT	OR	OFF	2004/07/13 19:48
S28	1	"6225688".PN.	USPAT	OR	OFF	2004/07/13 19:49
S29	1	"6262895".PN.	USPAT	OR	OFF	2004/07/13 19:49
S30	1	"6005778".PN.	USPAT	OR	OFF	2004/07/13 19:54
S31	1	"6100594".PN.	USPAT	OR	OFF	2004/07/13 19:55

S32	1	"6271598".PN.	USPAT	OR	OFF	2004/07/13 19:55
S33	1	"6333562".PN.	USPAT	OR	OFF	2004/07/13 20:04
S34	1	"6351028".PN.	USPAT	OR	OFF	2004/07/13 20:04
S35	1	"6359340".PN.	USPAT	OR	OFF	2004/07/13 20:04
S36	1	"6441496".PN.	USPAT	OR	OFF	2004/07/13 20:04
S37	1	"6545365".PN.	USPAT	OR	OFF	2004/07/13 20:04
S38	1	"6555902".PN.	USPAT	OR	OFF	2004/07/13 20:05
S39	1485	257/686 and (adhesive or glue or insert$3 or under near fill$3)	USPAT	OR	ON	2004/07/15 19:56
S40	1346	257/777 and (adhesive or glue or insert$3 or under near fill$3)	USPAT	OR	ON	2004/07/15 20:36
S41	1485	257/686 and (adhesive or glue or insert$3 or under near fill$3)	USPAT	OR	ON	2004/07/15 19:56
S42	630	(257/777 and (adhesive or glue or insert$3 or under near fill$3)) not (257/686 and (adhesive or glue or insert$3 or under near fill$3))	USPAT	OR	ON	2004/07/15 19:57
S43	3461	(361/760 or 438/108 or 438/109) and (adhesive or glue or insert$3 or under near fill$3)	USPAT	OR	ON	2004/07/15 20:37
S44	2181	(361/760) and (adhesive or glue or insert$3 or under near fill$3)	USPAT	OR	ON	2004/07/15 20:37
S45	1774	((361/760) and (adhesive or glue or insert$3 or under near fill$3)) not ((257/777 and (adhesive or glue or insert$3 or under near fill$3)) or (257/686 and (adhesive or glue or insert$3 or under near fill$3)))	USPAT	OR	ON	2004/07/19 17:37
S46	1	"5818107".PN.	USPAT	OR	OFF	2004/07/19 11:34
S47	1	"5872400".PN.	USPAT	OR	OFF	2004/07/19 11:34
S48	1	"6169328".PN.	USPAT	OR	OFF	2004/07/19 11:34
S49	1	"6175157".PN.	USPAT	OR	OFF	2004/07/19 11:34
S50	1	"6184062".PN.	USPAT	OR	OFF	2004/07/19 11:35
S51	1	"6184582".PN.	USPAT	OR	OFF	2004/07/19 11:35
S52	1	"6238949".PN.	USPAT	OR	OFF	2004/07/19 11:35
S53	1	"6271598".PN.	USPAT	OR	OFF	2004/07/19 11:35
S54	1	"6313998".PN.	USPAT	OR	OFF	2004/07/19 11:36
S55	1	"6392304".PN.	USPAT	OR	OFF	2004/07/19 11:36
S56	1	"6472758".PN.	USPAT	OR	OFF	2004/07/19 11:36
S57	1	"5269453".PN.	USPAT	OR	OFF	2004/07/19 11:50
S58	1	"6022792".PN.	USPAT	OR	OFF	2004/07/19 11:51

S59	2663	((361/760 or 438/108 or 438/109) and (adhesive or glue or insert$3 or under near fill$3)) not ((257/777 and (adhesive or glue or insert$3 or under near fill$3)) or (257/686 and (adhesive or glue or insert$3 or under near fill$3)))	USPAT	OR	ON	2004/07/19 17:37
S60	1774	((361/760) and (adhesive or glue or insert$3 or under near fill$3)) not ((257/777 and (adhesive or glue or insert$3 or under near fill$3)) or (257/686 and (adhesive or glue or insert$3 or under near fill$3)))	USPAT	OR	ON	2004/07/19 18:16
S61	889	(((361/760 or 438/108 or 438/109) and (adhesive or glue or insert$3 or under near fill$3)) not ((257/777 and (adhesive or glue or insert$3 or under near fill$3)) or (257/686 and (adhesive or glue or insert$3 or under near fill$3)))) not (((361/760) and (adhesive or glue or insert$3 or under near fill$3)) not ((257/777 and (adhesive or glue or insert$3 or under near fill$3)) or (257/686 and (adhesive or glue or insert$3 or under near fill$3))))	USPAT	OR	ON	2004/07/19 17:38
S62	143	mother near (chip or die or IC or semiconductor) and (adhesive or glue or insert$3 or under near fill$3)	USPAT	OR	ON	2004/07/19 18:24
S63	48	"4764804" and (adhesive or glue or insert$3 or under near fill$3)	USPAT	OR	ON	2004/07/19 18:24
S64	2651	257/686	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/07/19 18:35
S65	1422	257/686 and (adhesive or glue)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/07/19 18:36
S66	1229	257/686 not (257/686 and (adhesive or glue))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/07/19 18:36
S67	1	"5696031".pn.	USPAT	OR	OFF	2004/07/20 11:16

S68	1899	(semiconductor or die or chip or IC) and (wir$3 or conduct$3 or metal$7 or lead) with cover$3 with side with (semiconductor or die or chip or IC)	USPAT	OR	OFF	2004/07/20 14:03
S69	1	"5081520".PN.	USPAT	OR	OFF	2004/07/20 11:47
S70	1	"5224021".PN.	USPAT	OR	OFF	2004/07/20 11:48
S71	1	"5397916".PN.	USPAT	OR	OFF	2004/07/20 11:51
S72	1	"5413970".PN.	USPAT	OR	OFF	2004/07/20 11:51
S73	1	"5663596".PN.	USPAT	OR	OFF	2004/07/20 11:51
S74	1	"5801439".PN.	USPAT	OR	OFF	2004/07/20 11:52
S75	1	"5663596".PN.	USPAT	OR	OFF	2004/07/20 11:53
S76	1	"5801439".PN.	USPAT	OR	OFF	2004/07/20 11:53
S77	1	"5530286".PN.	USPAT	OR	OFF	2004/07/20 11:55
S78	1	"5554886".PN.	USPAT	OR	OFF	2004/07/20 11:56
S79	1	"5760471".PN.	USPAT	OR	OFF	2004/07/20 11:56
S80	40	"4,971,930" "5,530,282" "6,512,219"	USPAT	OR	OFF	2004/07/20 13:55
S81	29	"5224021"	USPAT	OR	OFF	2004/07/20 13:58
S82	29	"5801439"	USPAT	OR	OFF	2004/07/20 13:58
S83	1	"5363279".PN.	USPAT	OR	OFF	2004/07/20 14:02
S84	1	"5583375".PN.	USPAT	OR	OFF	2004/07/20 14:02
S85	1	"5744827".PN.	USPAT	OR	OFF	2004/07/20 14:02
S86	1	"5770888".PN.	USPAT	OR	OFF	2004/07/20 14:02
S87	13450	(semiconductor or die or chip or IC) and (wir$3 or conduct$3 or metal$7 or lead) with cover$3 with (semiconductor or die or chip or IC)	USPAT	OR	OFF	2004/07/20 14:04
S88	1730	(semiconductor or die or chip or IC) and (wir$3 or conduct$3 or metal$7 or lead) with cover$3 near (semiconductor or die or chip or IC)	USPAT	OR	OFF	2004/07/20 14:04
S89	73010	(semiconductor or die or chip or IC) and (wir$3 or conduct$3 or metal$7 or lead) with ("C" or "U")	USPAT	OR	OFF	2004/07/20 14:05
S90	6113	(semiconductor or die or chip or IC) and (wir$3 or conduct$3 or metal$7 or lead) with ("C" or "U") near (shap$2 or formed)	USPAT	OR	OFF	2004/07/20 14:06
S91	4774	(semiconductor or die or chip or IC) and (wir$3 or conduct$3 or metal$7 or lead) with ("C" or "U") near (shaped)	USPAT	OR	OFF	2004/07/20 14:09

S92	4763	(semiconductor or die or chip or IC) and (wir$3 or conduct$3 or metal$7 or lead) with ("C" or "U") adj1 (shaped)	USPAT	OR	OFF	2004/07/20 14:10
S93	817	((semiconductor or die or chip or IC) and (wir$3 or conduct$3 or metal$7 or lead) with ("C" or "U") near (shaped)) and "257"	USPAT	OR	OFF	2004/07/20 18:48
S94	357	((semiconductor or die or chip or IC) and (wir$3 or conduct$3 or metal$7 or lead) with ("C" or "U") near (shaped)) and "438"	USPAT	OR	OFF	2004/07/20 18:11
S95	581	((semiconductor or die or chip or IC) and (wir$3 or conduct$3 or metal$7 or lead) with ("C" or "U") near (shaped)) and "361"	USPAT	OR	OFF	2004/07/20 18:15
S96	1	"3873173".PN.	USPAT	OR	OFF	2004/07/20 18:20
S97	1	"4595794".PN.	USPAT	OR	OFF	2004/07/20 18:21
S98	1	"4692790".PN.	USPAT	OR	OFF	2004/07/20 18:21
S99	1	"4895523".PN.	USPAT	OR	OFF	2004/07/20 18:21
S100	1	"5395253".PN.	USPAT	OR	OFF	2004/07/20 18:21
S101	1	"5420461".PN.	USPAT	OR	OFF	2004/07/20 18:21
S102	1	"5433631".PN.	USPAT	OR	OFF	2004/07/20 18:21
S103	1	"5619067".PN.	USPAT	OR	OFF	2004/07/20 18:21
S104	1	"4595794".PN.	USPAT	OR	OFF	2004/07/20 18:23
S105	1	"4692790".PN.	USPAT	OR	OFF	2004/07/20 18:24
S106	1	"4895523".PN.	USPAT	OR	OFF	2004/07/20 18:24
S107	1	"5395253".PN.	USPAT	OR	OFF	2004/07/20 18:24
S108	1	"5395253".PN.	USPAT	OR	OFF	2004/07/20 18:24
S109	1	"5420461".PN.	USPAT	OR	OFF	2004/07/20 18:24
S110	1	"5433631".PN.	USPAT	OR	OFF	2004/07/20 18:24
S111	1	"5619067".PN.	USPAT	OR	OFF	2004/07/20 18:24

S11 2	817	((semiconductor or die or chip or IC) and (wir$3 or conduct$3 or metal$7 or lead) with ("C" or "U") near (shaped)) and "257"	USPAT	OR	OFF	2004/07/20 18:48
S11 3	4774	((semiconductor or die or chip or IC) and (wir$3 or conduct$3 or metal$7 or lead) with ("C" or "U") near (shaped))	USPAT	OR	OFF	2004/07/20 18:48
S11 4	3452	(((semiconductor or die or chip or IC) and (wir$3 or conduct$3 or metal$7 or lead) with ("C" or "U") near (shaped))) not ((((semiconductor or die or chip or IC) and (wir$3 or conduct$3 or metal$7 or lead) with ("C" or "U") near (shaped)) and "438") or (((semiconductor or die or chip or IC) and (wir$3 or conduct$3 or metal$7 or lead) with ("C" or "U") near (shaped)) and "361") or (((semiconductor or die or chip or IC) and (wir$3 or conduct$3 or metal$7 or lead) with ("C" or "U") near (shaped)) and "257"))	USPAT	OR	OFF	2004/07/20 18:49
S11 5	591	((((semiconductor or die or chip or IC) and (wir$3 or conduct$3 or metal$7 or lead) with ("C" or "U") near (shaped))) not ((((semiconductor or die or chip or IC) and (wir$3 or conduct$3 or metal$7 or lead) with ("C" or "U") near (shaped)) and "438") or (((semiconductor or die or chip or IC) and (wir$3 or conduct$3 or metal$7 or lead) with ("C" or "U") near (shaped)) and "361") or (((semiconductor or die or chip or IC) and (wir$3 or conduct$3 or metal$7 or lead) with ("C" or "U") near (shaped)) and "257"))) and "174"	USPAT	OR	OFF	2004/07/20 18:57

S116	1848	((((semiconductor or die or chip or IC) and (wir$3 or conduct$3 or metal$7 or lead) with ("C" or "U") near (shaped))) not (((((semiconductor or die or chip or IC) and (wir$3 or conduct$3 or metal$7 or lead) with ("C" or "U") near (shaped)) and "438") or (((semiconductor or die or chip or IC) and (wir$3 or conduct$3 or metal$7 or lead) with ("C" or "U") near (shaped)) and "361") or (((semiconductor or die or chip or IC) and (wir$3 or conduct$3 or metal$7 or lead) with ("C" or "U") near (shaped)) and "257"))) and "29"	USPAT	OR	OFF	2004/07/20 19:33
S117	640	257/726	USPAT	OR	OFF	2004/07/20 19:46
S118	1131	257/727	USPAT	OR	OFF	2004/07/20 20:04
S119	2034	257/777	USPAT	OR	OFF	2004/07/20 20:05
S120	1	"5508565".PN.	USPAT	OR	OFF	2004/07/20 20:42
S121	1	"5677567".PN.	USPAT	OR	OFF	2004/07/20 20:43
S122	1	"5744863".PN.	USPAT	OR	OFF	2004/07/20 20:43
S123	1	"5789815".PN.	USPAT	OR	OFF	2004/07/20 20:43
S124	2322	257/686	USPAT	OR	ON	2005/01/03 14:46
S125	1288	257/686 and (mold$3 or encapsula$3)	USPAT	OR	ON	2005/01/03 14:47
S126	1337	257/686 and (mold$3 or encapsula$4)	USPAT	OR	ON	2005/01/03 16:00
S127	1	"2001223326"	USPAT; JPO	OR	ON	2005/01/03 17:00
S128	1	"5293301".PN.	USPAT; USOCR	OR	OFF	2005/01/03 16:30
S129	1	"5644163".PN.	USPAT; USOCR	OR	OFF	2005/01/03 16:30
S130	1	"5726079".PN.	USPAT; USOCR	OR	OFF	2005/01/03 16:31
S131	1	"5815372".PN.	USPAT; USOCR	OR	OFF	2005/01/03 16:31

S13 2	1	"5866943".PN.	USPAT; USOCR	OR	OFF	2005/01/03 16:31
S13 3	1	"5909057".PN.	USPAT; USOCR	OR	OFF	2005/01/03 16:32
S13 4	1	"6143590".PN.	USPAT; USOCR	OR	OFF	2005/01/03 16:32
S13 5	1	"6359341".PN.	USPAT; USOCR	OR	OFF	2005/01/03 16:32
S13 6	1	"6388340".PN.	USPAT; USOCR	OR	OFF	2005/01/03 16:33
S13 7	1	"6472741".PN.	USPAT; USOCR	OR	OFF	2005/01/03 16:33
S13 8	1	"6501164".PN.	USPAT; USOCR	OR	OFF	2005/01/03 16:33
S13 9	1	"6005778".PN.	USPAT; USOCR	OR	OFF	2005/01/03 16:35
S14 0	3	"10291695" or "11096812"	USPAT; JPO	OR	ON	2005/01/03 17:03
S14 1	1	"20020094608"	US-PGPUB; USPAT; JPO	OR	ON	2005/01/03 17:11
S14 2	2	"6617198"	US-PGPUB; USPAT; JPO	OR	ON	2005/01/03 17:12
S14 3	2937	257/686	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/04 19:40
S14 4	1240	257/685	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/04 20:22
S14 5	2712	257/777	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/04 20:06
S14 6	2324	438/108	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/04 20:51

S147	1117	438/109		US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/04 21:11
S148	3959	361/760		US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/04 21:12